

LEADED

BGA SOLDER PASTE



Sn63/Pb37

Melting point 183°C



Product Usage

TIN PASTE

Type number	BST-506-JP
Types of	Solder Paste
Composition	Sn63/Pb37
Melting point	183°C
G.W.	50g
size	1.24*1.49 in





Product List

G.W.:50g

